

Minutes from OpenPICs WP 4 meeting 13-11-2017

Present: Victor (chairing), Rob, Roel, Weiming, Kevin

Time: 13:30-14:30

Discussion/action points

Nr.	Description	Responsible
1.	Al-MQW Design Initial simulation results on Al-based QW shown Growth of first Al-wafers → December (1 st week)	Weiming
2	Zn-diffusion experiments Zn-diffusion experiments done: Test 1: Samples with different diffusion times Test 2: Planar diffusion on wafer for homogeneity check Others: Diffusion on patterned wafer tbd after maintenance weeks	Rene, Victor
3	Thick BCB (high performance RF lines) Test needed for adhesion of metal on BCB: Test 1: metal/SiO _x /BCB/SiO _x /Si → tape test OK → wedge bonding OK Test 2: metal/BCB/Si → tape test OK → wedge bonding NOT OK Test 3: metal/(etched)BCB/Si → tape test OK → wedge bonding NOT OK Next: Samples for characterization → metal/SiO _x /BCB/SiO _x /InP, metal/SiO _x /InP	Tjibbe, Victor
4	Process of MaN resist for Stepper Standard recipe tested. Samples with different development time done and cross sections were checked.	Robert, Victor
5	Meetings Expectation: management aspects (e.g. project timeline) should be more clear.	Rob, Victor